Wednesday, May 8th

18:30   **Steering Committee Meeting**

19:30   **Welcome Party**

Thursday, May 9th

08:30   **Opening Session + Keynote Session 1**
             Room: **Conference Room**
             Chair: **Heinz Wohlrabe, Emilian Ceuca**

08:50	**Web based Teaching Tools of Electronics Technology** **G. Harsanyi,** *Budapest University of Technology and Economics*
09:30	**Reliability of Power Electronics System for Electro Mobility** **K. Wolter,** *Technische Universitat Dresden, Germany*

10:10   **Coffee Break**

10:30   **Bosch Presentation**

10:45   **Keynote Session 2**
             Room: **Conference Room**
             Chair: **Gabor Harsanyi, Klaus-Jürgen Wolter**

10:45	**Sensors for Autonomous Driving – from Research to Series Production** **O. Sbanski,** *Robert Bosch GmbH*
11:25	**Silicon Carbide (SiC) Devices for Automotive Applications** **G. Brezeanu,** *Politehnica University Bucharest*

12:05   **Lunch Break**

13:05   **Oral Session 1**
             New Materials and Processes + Process Modeling and Simulation
             Room: **Conference Room**
             Chair: **Alena Pietrikova, Norocel Codreanu**

13:05 A03	**New Method for Adjustment of Elevation of the Ceramic Flatness for Direct Deposition** **M. Buršík, J. Jankovský, M. Řezníček, I. Szendiuch,** *Brno University of Technology*
13:30 A05	**Optimized Thin–Film Diffusion Soldering for Electronics Production** **A. Syed Khaja, A. Reinhardt, J. Franke,** *Institute FAPS, University Erlangen-Nuremberg*
13:55 E16	**Thermo-mechanical Sub-modelling of BGA Components in PCB Reflow** **S. Stoyanov, C. Bailey,** *University of Greenwich*
14:20 E22	**Modeling of Condensation Heating During Vapour Phase Soldering** **A. Geczy, B. Illés, Z. Illyefalvi-Vitéz,** *Budapest University of Technology and Economcis*

14:45 Coffee Break

15:05 Poster Session 1

New Materials and Processes + Process Modeling and Simulation Part I

Room: Poster Room

Chair: Dan Pitica, Zsolt Illeyfalvi-Vitez

A01	**Experimental Setup for the Characterization of the Percolation Behavior of Wet Conductive Coatings by High Frequency Eddy Current Spectroscopy** **I. Patsora, H. Heuer, S. Hillmann, D. Tatarchuk, B. Foos,** *Technische Universität Dresden*
A02	**Method for Automatic Material Testing with Diagnostic Imaging Ultrasound** **O. Punk, T. Höhndorf, H. Heimbach, U. Heuert,** *University of Applied Sciences Merseburg, Department of Engineering and Natural Sciences*
A04	**Influence of Nanosilver Production Technology on Parameters of Ink–Jet Printed Conducting Layers on Flexible Substrates** **M. Zawierta, A. Smolarek, T. Fałat, J. Felba, A. Mościcki, Z. Żaluk,** *Faculty of Microsystem Electronics and Photonics, Wroclaw University of Technology, Poland*
A06	**Optimization of the Spray Polyphenylene Vinylene Thin Film Deposition** **V. Milenkov, I. Zhivkov, R. Yordanov, I. Yordanova, D. Mladenova, M. Weiter,** *Faculty of Chemistry, Centre for Materials Research, Brno University of Technology*
A07	**Characterization of Ferrite LTCC Tapes** **M. Franz, S. Lueftl, A. Maric, I. Atassi, N. Blaž, M. Hrovat, K. Makarovic, G. Radosavljevic,** *Vienna University of Technology*
A09	**Influence of the Deposition Process Parameters on Electrophysical Properties of Al2O3 Thin Films** **P. Firek, J. Gryglewicz, J. Jasiński,** *Institute of Microelectronics and Optoelectronics, Warsaw University of Technology*
A10	**The Mischmetal and Bi94Zn6 Effect Alloying on SACX 0307** **M. Branzei, I. Pencea, I. Plotog, F. Miculescu, I. Cristea, A. Thumm,** *UPB - CEMS*
E01	**Advanced Methods of Generating Signals to Command Switching Convertors** **I. Baciu, L. Viman, A. Fodor,** *Technical University of Cluj-Napoca*
E02	**Usage of LTCC Technology in Electronic Packaging** **B. Psota, M. Klíma, M. Nicák, I. Szendiuch,** *BUT Brno*
E04	**Simulation of the ZnO MEMS Disk Asymmetric Vibration Resonant Frequencies Values** **I. Ianovska, O. Bogdan, O. Petrishev, Y. Yakimenko,** *National Technical University of Ukraine "KPI"*
E05	**Physical Implementation, Parasitic Extraction and Parameter Comparison of LNA with Two Types of ESD Protection Structures** **I. Toteva, A. Andonova,** *Technical University of Sofia*
E06	**Behavioral Modeling of Polycrystalline Module ET-P660230WW** **G. Angelov, R. Rusev, A. Andonova, M. Hristov,** *Technical University of Sofia NIS*
E07	**Hybrid Simulation in Intelligent Transportation Systems** **F. Nemtanu, I. Moise, C. Banica,** *University Politehnica of Bucharest*
E08	**Techniques for Analysing the Variance of the Heart Rhythm Within the Time–Frequency Area** **C. Banica, C. Seritan, I. Moise, F. Nemtanu,** *University Politehnica of Bucharest*

16:35   Coffee Break

16:55   Poster Session 2
Process Modeling and Simulation Part II
Room: Poster Room
Chair: Balazs Illes, Ciprian Ionescu

E09	**Simulation of Ultrasonic Sensor Parameters for Material Testing on Plastic** **T. Höhndorf, O. Punk, H. Heimbach, U. Heuert,** *UAS Merseburg*
E10	**Modeling Photonic Crystal Fiber With Low Birefrigence Using Fast Multipole Method** **Y. Bashkatov, O. Kutsenko, B. Tsyganok,** *National Technical University of Ukraine "KPI"*
E11	**Investigation of Stimulated Raman Scattering in Microstuctured Fibers** **Y. Bashkatov, K. Yershov, V. Khomenko, V. Voitsekhovich, N. Kachalova, B. Tsyganok,** *National Technical University of Ukraine "KPI"*
E12	**A Digitally Controlled Programmable Power Supply Used in a Vaporizer** **R. Etz, D. Petreus, T. Frentiu, T. Patarau,** *Applied Electronics Department, Tehnical University of Cluj-Napoca*
E13	**Design of Microstrip Band Pass Filter Based on LTCC for UWB Sensor System** **K. Ruman,** *Technical University of Kosice*
E14	**Design of Narrowband 2.4 – 2.5 GHz Notch Filter Using Various Materials** **A. Pietrikova,** *Technical University of Kosice*
E15	**Study of Sputtering Process of Alumina Thin Films** **P. Mach, M. Kocian,** *CTU Prague, Czech Republic*
E17	**Coarse Grained Molecular Dynamics Study of Heat Transfer in Thermal Interface Materials** **M. Zawierta, B. Płatek, T. Fałat, J. Felba,** *Faculty of Microsystem Electronics and Photonics,Wroclaw University of Technology, Wroclaw, Poland*
E18	**Medium Power Buck-Boost Converter for Solar Application** **D. Filip, D. Petreus,** *University of Cluj-Napoca*
E20	**Design and Modeling of 13.56 MHz RFID Antenna in Ink-Jet Printing Technology** **M. Kisic,** *University of Novi Sad, Faculty of Technical Sciences*
E21	**Representative Subschema Extraction Method for Schemas in Technological Applications** **B. Villányi, P. Martinek,** *Budapest University of Technology and Economics*
E23	**Device Mismatch Analysis and Effect Compensation in Fundamental Analog Cells** **P. Farago, D. Bogăţeanu, E. Ceuca, C. Moisă, S. Hintea,** *Technical University of Cluj-Napoca*
E24	**Model of Cloudified Traveller Information System Based on Petri Nets** **F. Nemtanu, I. Moise, M. Beldescu, V. Iordache,** *University Politehnica of Bucharest*
E25	**Stochastic Model for Analysis Transport Systems** **E. Ciortea,** *"1 Decembrie 1918" University of Alba Iulia*

E26	**Controlling Procedure for Underwater Robots in Autonomous Mode** **I. Farkas, E. Ceuca, A. Tulbure,** *"1 Decembrie 1918" University of Alba Iulia*
E27	**Analysis and Simulation of LCLR Converters** **O. Pop, A. Taut, A. Grama, E. Ceuca,** *Applied Electronics Department, Technical University of Cluj-Napoca*
E28	**Behavioural Macromodels for RMS and Average Value Calculus in DC–DC Converters** **M. Cîrlugea, S. Hintea, E. Ceuca, P. Farago,** *Applied Electronics Department, Technical University of Cluj-Napoca*

18:25   Dinner

Friday, May 10th

8:00   Oral Session 2

Testing, Reliability and Quality
Room: Conference Room
Chair: Heinz Wohlrabe, Pavel Mach

08:00 D03	**Electrical Stress on Transparent Conductive Oxide Layer** **D. Bonfert, D. Hemmetzberger, G. Klink, K. Bock, C. Ionescu, P. Svasta,** *Fraunhofer EMFT*
08:25 D06	**Absorption and Diffusion of Water in Printed Circuit Boards** **H. Zecha, T. Zerna,** *Robert Bosch GmbH Schwieberdingen*
08:50 D20	**Characterization of dielectric LTCC tapes** **G. Mišković, S. Toskov, A. Marić, N. Blaž, G. Radosavljevic,** *Vienna University of Technology*

09: 15   Altium Designer Presentation

09: 25   Coffee Break

09: 45   Keynote Session 3

Room: Conference Room
Chair: Johan Nicolics, Paul Svasta

09:45	**New Trends in µController Technology – Better, Faster, Smaller, Lower Power/Cost Embedded Solutions** **D. Chiricescu,** *Microchip Technology srl, Romania*
10:25	**Enablers for Automotive Electronics Packaging** **J. Haidar,** *Infineon Technologies Romania & CO SCS*

11:05   Coffee Break

11:25   Emerson Presentation

11:55   Poster Session 3

Thermal Management + Advanced Packaging and Interconnection Technologies + Nanomaterials and Nanoelectronics, Testing, Reliability and Quality

Room: Poster Room

Chair: Detlef Bonfert, Ryzsard Kisiel

B01	**Thermal Management of Embedded Devices** **J. Rajmond, A. Fodor,** *Applied Electronics Dept*
B03	**Optimization of a Heater Geometry for Flexible Gas Sensor Applications** **D. Bonfert, N. Codreanu, P. Svasta, C. Ionescu,** *Fraunhofer Institution for Modular Solid State Technologies (EMFT)*
B04	**Method for in-situ High- Flux LED Arrays Thermal Loading Testing** **P. Mashkov, T. Pencheva , B. Gyoch,** *University of Ruse*
B06	**Thermal Modeling of Furnace–Runner Camera System** **T. Hurtony, Á. Gyovai, P. Gordon,** *Budapest University of Technology and Economics*
B07	**Omnidirectional Infrared Illuminator for a 360–Degree Vision System** **M. Vladescu, P. Stroica,** *University "Politehnica" of Bucharest, Romania*
C03	**Parameters of the Manufacturing Process and Reliability of Embedded Components** **S. Osmolovskyi, R. Schwerz, K. Wolter,** *Electronics Packaging Laboratory, Technische Universität Dresden*
C04	**Polymer Thick Film Technology and Its Capability for Medicine and Sensor Applications** **M. Luniak, M. Varga, K. Wolter,** *TU Dresden, IAVT*
C05	**3D structure with opened cavity in Low Shrinkage LTCC** **M. Štekovič, J. Šandera,** *Brno University of Technology*
C06	**Investigations on Ultrasonic Copper Wire Wedge Bonding for Power Electronics** **C. Kaestle, A. Reinhardt, J. Franke,** *Friedrich-Alexander-Universität Erlangen-Nürnberg, Lehrstuhl für Fertigungsautomatisierung und Produktionssystematik*
C07	**Testing of Usability of Tabbed Ribbons Adhesive Assembly in PV Modules Production** **P. Mach, J. Janak,** *CTU Prague, Czech Republic*
C09	**Investigating Copper Wire Bonding Technology in Chip-on-Board Applications** **O. Krammer, P. Róka,** *Budapest University of Technology and Economics*
F01	**Lead–Free Thick Film Resistors on Alumina and LTCC Substrates** **M. Hrovat,** *Jozef Stefan Institute Ljubljana*
F02	**The Power Quality Influence on the Reliability of PFC Capacitors** **A. Tulbure, E. Ceuca, C. Farcas, I. Farkas,** *"1 Decembrie 1918" University of Alba Iulia*
F03	**System for Energy Recovering with BLDC Motor at Deceleration Momentum** **A. Taut, O. Pop, E. Ceuca,** *Applied Electronics Department, Tehnical University of Cluj-Napoca*
F04	**Embedded System for Remote Monitoring of OBD Bus** **E. Ceuca, A. Tulbure, A. Taut, O. Pop, I. Farkas,** *Department of Electronics, "1 DECEMBRIE 1918" University of Alba Iulia*

G01	**Hydrogen Storage Capacity of Carbon Nanotubes γ – Irradiated in Hydrogen and Deuterium Media** **I. Uvarova, R. Basnukaeva, A. Dolbin, B. Danilchenko,** *Institute of Physics NASU Kiew*
G02	**Temperature Dependences of the Dielectric Permittivity and Dissipation Factor for Nanocomposites Metal–Polymer** **Y. Didenko, D. Tatarchuk, I. Kharabet, A. Franchuk, Y. Yakimenko,** *National Technical University of Ukraine "KPI"*
G03	**An AFM Study Regarding the Effect of Annealing on the Microstructure of Gold Thin Films** **A. Bonyár, P. Lehoczki,** *Budapest University of Technology and Economics, Department of Electronics Technology*
G04	**Graphene and its Potential Applications in Electronics Packaging – A Review** **Z. Illyefalvi-Vitéz,** *Budapest University of Technology and Economics*

13:25   Lunch Break

14:30   Culture Program

TRIP to TURDA
Visit of the Turda Salt Mine: a real museum of salt mining in Transylvania (Bus trip)

18:30   Dinner at Turda

Saturday, May 11th

08:00   Poster Session 4
Testing, Reliability and Quality Part I
Room: Poster Room
Chair: Oliver Krammer, Ivan Szendiuch

D01	**Integrated Circuits Characterization Platform (ICCP)** **C. Tamas, M. Pantazica, C. Grecu, I. Marghescu,** *Telecommunication Department, UPB*
D02	**Comparing the IMC layer growth in Sn-Cu, Sn-Ag-Cu and Sn-Ni-Cu layer systems** **B. Illés, B. Horváth,** *Budapest University of Technology and Economics*
D04	**Evaluation of the Fracture Behaviour of SMT–Components by Electrical Measurements** **M. Kyrychenko, H. Wohlrabe, S. Meyer, H. Reuter, M. Keil,** *TU Dresden, Electronics Packaging Lab*
D05	**Safety Analysis of the New Command-Control Systems Implemented in the Bulgarian Railway Infrastructure Company** **M. Georgieva, N. Stoytcheva,** *Department of Telecommunication and Signalling, University of Transport, Sofia*
D07	**Compatibility of Through-Hole Technology Devices with Low-Temperature Co-fired Ceramic Substrate** **M. Klima, B. Psota, I. Szendiuch,** *Brno University of Technology*

D08	**Influence of Type of Reflow Technology and Type of Surface Finish on Tomb Stone Effect** **K. Dušek, V. Straka,** *FEE CTU in Prague, Department of Electrotechnology*
D10	**Effect of Reflow Technology and Surface Finishes of PCB on Solder Spreading** **K. Dušek, M. Vávra, A. Rudajevová,** *FEE CTU in Prague, Department of Electrotechnology*
D11	**Evaluation of the Effects of the Layout Design on the Quality of SMT Boards** **M. Pantazica, C. Marghescu, C. Tamas, H. Wohlrabe, K. Wolter, P. Svasta,** *UPB-CETTI*
D12	**Study of Atmosphere Influence on BGA Solder Balls Process** **A. Otáhal, I. Szendiuch,** *Brno University of Technology*
D13	**Ageing of Tunnel Junctions Formed in Oxygen Plasma and in Air** **P. Mach, T. Rozkosny,** *CTU Prague, Czech Republic*
D14	**Contact Angle Measurements on FR4 and Polyimide Substrates relating Electrochemical Migration** **B. Medgyes, B. Illés, L. Gál,** *Budapest University of Technology and Economics*
D15	**Investigating Micro-alloyed Solder Joints with Electrochemical Etching** **T. Garami, O. Krammer,** *Budapest University of Technology and Economics*
D16	**Evaluation of Solder Joints Formed by Different Vapour Phase Soldering Systems** **Z. Peter, A. Geczy, M. Ruszinko, D. Rigler, Z. Illyefalvi-Vitéz,** *Budapest University of Technology and Economcis*
D17	**Efficiency Testing of ESD Protection System** **T. Blecha,** *University of West Bohemia in Pilsen, Faculty of Electrical Engineering*
D18	**Agile Product Design – A Modern Approach to Quality Improvement** **M. Molhanec,** *Czech Technical University in Prague*
E03	**Arbitrarily Shaped Coils' Inductance Simulation Based on a 3–Dimensional Solution of the Biot–Savart Law** **C. Volkmar, T. Baruth, J. Simon, U. Ricklefs, R. Thüringer,** *Technische Hochschule Mittelhessen University of Applied Sciences*

09:30   **Coffee Break**

09:50   **Poster Session 5**

        Testing, Reliability and Quality Part II + Signal Integrity and Electromagnetic Compatibility + Sensors, Actuators and Microsystems Part I
        Room: **Poster Room**
        Chair: **Dorin Petreus, Balazs Illes**

D19	**Model Based FMEA Method for Solar Modules** **M. Molhanec,** *Czech Technical University in Prague*
D21	**On Change Detection based on Fusion of Acoustic and Vibration Signal Processing** **D. Aiordachioaie,** *Dunarea de Jos University of Galati*
D22	**Processing the Squib Energy Data** **S. Gavrila, A. Gontean,** *University "Politehnica" Timisoara*

D23	**Multiconvolutional Approach for Uncertainty Estimation of the Thermal Diffusivity Measured by Flash Method** **M. Brânzei, I. Pencea, I. Plotog, M. Branzei, A. Bibis, P. Svasta,** *UPB – CEMS*
H01	**Controller for Reducing the EMI in Gas Gauge and Battery Management Units** **C. Tamas, M. Pantazica , C. Marghescu , I. Marghescu,** *Telecommunication Department, UPB*
H02	**Solving an EMC/EMI Problem Occurred Inside a CPLD** **D. Vuza, M. Vladescu,** *Institute of Mathematics of the Romanian Academy, Bucharest, Romania,*
I01	**Electrical Model of a Capacitive Based Level Sensor** **V. Bande, S. Pop, D. Pitică, I. Ciascai,** *Technical University of Cluj Napoca*
I02	**Electronic Measurement and Registration System of Hydraulic Dampers Test Stand** **N. Dodev, N. Nenov, E. Dimitrov, P. Karabashki,** *University of Transport (VTU)*
I03	**9DoF IMU/GPS/GSM System for Evaluation of the Bogie–Railway System Dynamics** **E. Iontchev, R. Kenov, R. Miletiev, B. Valkov,** *VTU "T. Kableshkov"*
I04	**Portable Measurement System for Silicon Nanowire Field–Effect Transistor–Based Biosensors** **T. Voitsekhivska, E. Suthau, K. Wolter, F. Zörgiebel, L. Baraban, G. Cuniberti,** *Technische Universität Dresden*
I06	**High Accuracy Method for Measurement of Vibrating Wire Transducer** **S. Pop, I. Ciascai, V. Bande, D. Pitică,** *Technical University of Cluj-Napoca, Applied Electronics Department*
I07	**Application of Electronic Measurement Equipment SPIDER 8 (HBM)** **When Testing the Susceptibility of Steels to Cold Weld Cracking** **E. Tasheva, R. Merdzhanov, P. Tashev, I. Savova,** *Institute of Metal Science, equipment and technologies Bulgarian Academy of Sciences*
I12	**Electronic Module for Operation Monitoring of a Mechano- Hydraulic System of Rotation Kinetic Energy Recovery** **C. Cristescu, R. Radoi, I. Dutu, G. Matache, I. Ilie,** *INOE 2000 IHP*
I13	**Temperature Compensated Field Bus Sensor Interface for Applications in Process Engineering** **E. Suthau, S. Hildebrandt, K. Wolter,** *Electronics Packaging Laboratory, Technische Universität Dresden*
I14	**Low Frequency Pulsed Magneto Therapy Microsystem** **D. Petreus, T. Patarau, R. Etz, E. Kiraly, P. Baru,** *Applied Electronics Department, Tehnical University of Cluj-Napoca*
I15	**Performance Improvement of LTCC Capacitive Displacement Sensor** **N. Blaž,** *University of Novi Sad, Faculty of Technical Sciences*

11:20   Guard Change Ceremony

12:15 Poster Session 6

Sensors, Actuators and Microsystems Part II + Educational and Information Activities in Electronics Technologies

Room: Poster Room

Chair: Philipp Philipov, Nencho Nenov

I16	**Operational Tests of a Wireless Fetal Pulse Oximeter** N. Stuban, *Budapest University of Technology*
I17	**Implementation of Charge Sensitive Amplifier/Discriminator for PIN Diode Radiation Detectors** I. Cioc, C. Talpalariu, C. Matei, I. Lita, D. Visan, *University of Pitesti*
I18	**Data Acquisition System for Collision Tests in Automotive Industry** I. Lita, D. Visan, I. Cioc, V. Ionescu, R. Teodorescu, *University of Pitesti*
I19	**Architecture for Adders in Digital Filters Operating in Mixed Power Modes** V. Ionescu, I. Lita, D. Visan, I. Cioc, *University of Pitesti*
I20	**Design of Digital Communication Module for Remote Measurement Systems** D. Visan, I. Lita, I. Cioc, V. Ionescu, *University of Pitesti*
I21	**Control of Industrial Systems using Android-based Devices** A. Drumea, *Department of Electronics Technology, "Politehnica" University Bucharest*
I22	**Strain Sensor in Ink-Jet Printing Technology** Č. Žlebič, *University of Novi Sad, Faculty of Technical Science*
J01	**An Educational Tool for Understanding Reflections and Crosstalk** M. Dărăban, D. Pitică, A. Taut, *Applied Electronics Department, Tehnical University of Cluj-Napoca*
J02	**2D and 3D Representations of the Noise in a PCB using Analytical Methods** R. Fizesan, D. Pitică, O. Pop, *Applied Electronics Department, Tehnical University of Cluj-Napoca*
J03	**A Matlab Tool for Determining the Parameters of Power DC-DC Non Isolated Converters** A. Taut, O. Pop, I. Baciu, M. Dărăban, *Applied Electronics Department, Tehnical University of Cluj-Napoca*
J04	**The Gamification of the Study of Electronics in Specialized E–Learning Platforms** V. Todor, D. Pitică, *Faculty of Electronics, Telecommunication and Information Technology, Technical University of Cluj-Napoca*
J06	**Educational VHF/UHF Ground Station for LEO Satellite University Missions** P. Dascal, *Technical University of Cluj-Napoca, Faculty of Electronics, Telecommunication and Information Technology*
J07	**VLF Radio Wave Monitoring Equipment for Educational Purposes** P. Dolea, *BITNET CCSS Cluj-Napoca*
J09	**UV Laboratory Platform for Treatment of Photosensitive Materials** R. Dobre, N. Codreanu, *"Politehnica" University of Bucharest*
J10	**Electronic Packaging Education using Open-Source and Free Software Tools** A. Drumea, *Department of Electronics Technology, "Politehnica" University Bucharest*

13:35   **Lunch Break**

14:35   **Oral Session 3**

Advanced Packaging and Interconnection Technologies
Room: **Conference Room**
Chair: **Stoyan Stojanov, Boris Tsyganok**

14:35 C01	**Process Optimization and Characterization of a Novel Micro–Scaled Silver Sintering Paste as a Die–Attach Material for High Temperature High Power Semiconductor Devices** **A. Bajwa, J. Wilde,** *Albert Ludwigs University of Freiburg*
15:00 C02	**Design, Fabrication and Characterization of Three-Dimensional Microcoils in LTCC Technology** **P. Krivic, M. Weilguni,** *Institute of Sensor and Actuator Systems, Vienna Univesity of Technology*
15:25 C08	**Aspects of Applying Flip-chip Technology for SiC Power Devices Assembly** **M. Myśliwiec, M. Guziewicz, R. Kisiel,** *Warsaw University of Technology, IMiO*

15:50   **Coffee Break**

16:05   **Oral Session 4**

Thermal Management and LTCC-Sensors
Room: **Conference Room**
Chair: **Jan Felba, Marco Hrovat**

08:00 B05	**Design and Fabrication of Pt Micro-Heater built on Alumina Substrate** **S. Toskov,** *Vienna University of Technology*
16:05 I05	**Highly–Sensitive Flow Sensor in LTCC** **C. Lohrberg,** *Fraunhofer IKTS Dresden*
16:35 K01	**High Quality Spiral Transformer Embedded in LTCC Substrate** **A. Maric, G. Radosavljevic, N. Blaž, L. Zivanov,** *University of Novi Sad, Faculty of Technical Sciences, Department of Electronics*

17:30   **Culture Program – Part I - Apulum Garda Show**

18:00   **Culture Program – Part II - Classic Guitar Concert in Catholic Cathedral**

Alternative Program for Steering Committee

18:00   **Steering Committee Meeting**

20:30   **Conference Gala Dinner**